

CSD19537Q3 100V N 通道 NexFET™ 功率 MOSFET

1 特性

- 超低 Q_g 和 Q_{gd}
- 低热阻
- 雪崩级
- 无铅端子镀层
- 符合 RoHS
- 无卤素
- 小外形尺寸无引线 (SON) 3.3mm × 3.3mm 塑料封装

2 应用

- 一次侧隔离式转换器
- 电机控制

3 说明

这款 100V 12.1mΩ SON 3.3mm × 3.3mm NexFET™ 功率 MOSFET 旨在用于更大限度地降低功率转换应用中的损耗。

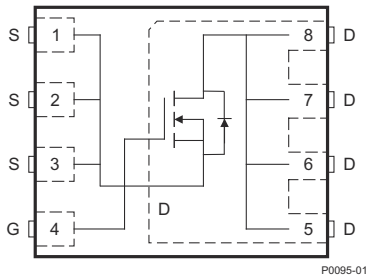
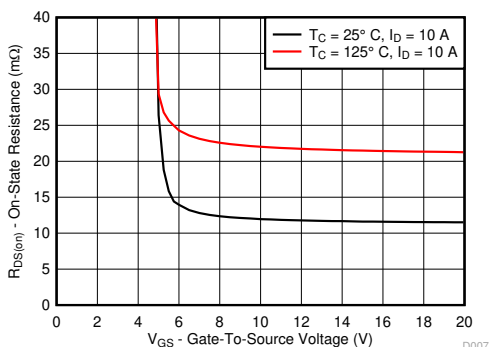


图 3-1.
顶视图



$R_{DS(on)}$ 与 V_{GS} 之间的关系

产品概要

$T_A = 25^\circ\text{C}$		典型值	单位
V_{DS}	漏源电压	100	V
Q_g	栅极电荷总量 (10V)	16	nC
Q_{gd}	栅极电荷 (栅极到漏极)	2.9	nC
$R_{DS(on)}$	漏源导通电阻	$V_{GS} = 6\text{V}$	13.8 mΩ
		$V_{GS} = 10\text{V}$	12.1 mΩ
$V_{GS(th)}$	阈值电压	3	V

订购信息⁽¹⁾

器件	介质	数量	封装	配送
CSD19537Q3	13 英寸卷带	2500	SON 3.3mm x 3.3mm 塑料封装	卷带包装
CSD19537Q3T	13 英寸卷带	250		

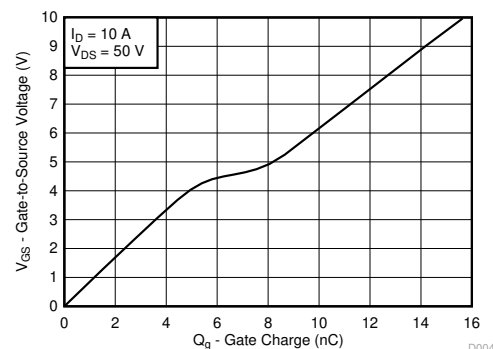
(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。

绝对最大额定值

$T_A = 25^\circ\text{C}$		值	单位
V_{DS}	漏源电压	100	V
V_{GS}	栅源电压	±20	V
I_D	持续漏极电流 (受封装限制)	50	A
	持续漏极电流 (受芯片限制), $T_C = 25^\circ\text{C}$ 时测得	53	A
	持续漏极电流 ⁽¹⁾	9.7	A
I_{DM}	脉冲漏极电流 ⁽²⁾	219	A
P_D	功耗 ⁽¹⁾	2.8	W
	功率耗散, $T_C = 25^\circ\text{C}$	83	W
T_J , T_{stg}	工作结温, 贮存温度	-55 至 150	°C
E_{AS}	雪崩能量, 单脉冲 $I_D = 33\text{A}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$	55	mJ

(1) $R_{\theta JA} = 45^\circ\text{C/W}$, 这是在 0.06 英寸厚 FR4 PCB 上的 1 平方英寸、2oz 铜焊盘上测得的典型值。

(2) 最大 $R_{\theta JC} = 1.5^\circ\text{C/W}$, 脉冲持续时间 $\leq 100 \mu\text{s}$, 占空比 $\leq 1\%$ 。



栅极电荷



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4 Revision History

Changes from Revision A (May 2016) to Revision B (November 2022)	Page
• Corrected legend on 图 5-11	4

Changes from Revision * (August 2015) to Revision A (May 2016)	Page
• Corrected typo in X axis legend on 图 5-11	4

5 Specifications

5.1 Electrical Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise stated)

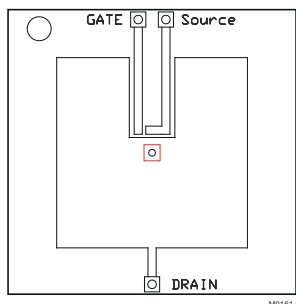
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV _{DSS}	Drain-to-source voltage	V _{GS} = 0 V, I _D = 250 μA	100			V
I _{DSS}	Drain-to-source leakage current	V _{GS} = 0 V, V _{DS} = 80 V	1			μA
I _{GSS}	Gate-to-source leakage current	V _{DS} = 0 V, V _{GS} = 20 V	100			nA
V _{GS(th)}	Gate-to-source threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.6	3	3.6	V
R _{DS(on)}	Drain-to-source on-resistance	V _{GS} = 6 V, I _D = 10 A	13.8		16.6	mΩ
		V _{GS} = 10 V, I _D = 10 A	12.1		14.5	mΩ
g _{fs}	Transconductance	V _{DS} = 10 V, I _D = 10 A	45			S
DYNAMIC CHARACTERISTICS						
C _{iss}	Input capacitance	V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	1290		1680	pF
C _{oss}	Output capacitance		251		326	pF
C _{rss}	Reverse transfer capacitance		13.3		17.3	pF
R _G	Series gate resistance		1.2		2.4	Ω
Q _g	Gate charge total (10 V)	V _{DS} = 50 V, I _D = 10 A	16		21	nC
Q _{gd}	Gate charge gate-to-drain		2.9			nC
Q _{gs}	Gate charge gate-to-source		5.5			nC
Q _{g(th)}	Gate charge at V _{th}		3.8			nC
Q _{oss}	Output charge	V _{DS} = 50 V, V _{GS} = 0 V	44			nC
t _{d(on)}	Turn on delay time	V _{DS} = 50 V, V _{GS} = 10 V, I _{DS} = 10 A, R _G = 0 Ω	5			ns
t _r	Rise time		3			ns
t _{d(off)}	Turn off delay time		10			ns
t _f	Fall time		3			ns
DIODE CHARACTERISTICS						
V _{SD}	Diode forward voltage	I _{SD} = 10 A, V _{GS} = 0 V	0.8		1	V
Q _{rr}	Reverse recovery charge	V _{DS} = 50 V, I _F = 10 A, di/dt = 300 A/ μs	134			nC
t _{rr}	Reverse recovery time		36			ns

5.2 Thermal Information

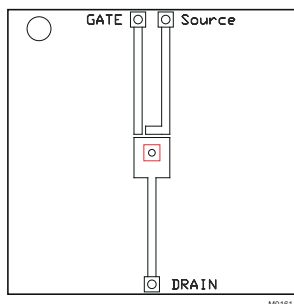
$T_A = 25^\circ\text{C}$ (unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-case thermal resistance ⁽¹⁾			1.5	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-ambient thermal resistance, Note 1 and Note 2 ^{(1) (2)}			55	$^\circ\text{C}/\text{W}$

- (1) $R_{\theta JC}$ is determined with the device mounted on a 1-in² (6.45-cm²), 2-oz (0.071-mm) thick Cu pad on a 1.5-in $\times$ 1.5-in (3.81-cm $\times$ 3.81-cm), 0.06-in (1.52-mm) thick FR4 PCB. $R_{\theta JC}$ is specified by design, whereas $R_{\theta JA}$ is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-in² (6.45-cm²), 2-oz (0.071-mm) thick Cu.



Max $R_{\theta JA} = 55^{\circ}\text{C/W}$ when mounted on 1 in² (6.45 cm²) of 2-oz (0.071-mm) thick Cu.



Max $R_{\theta JA} = 160^{\circ}\text{C/W}$ when mounted on a minimum pad area of 2-oz (0.071-mm) thick Cu.

5.3 Typical MOSFET Characteristics

$T_A = 25^{\circ}\text{C}$ (unless otherwise stated)

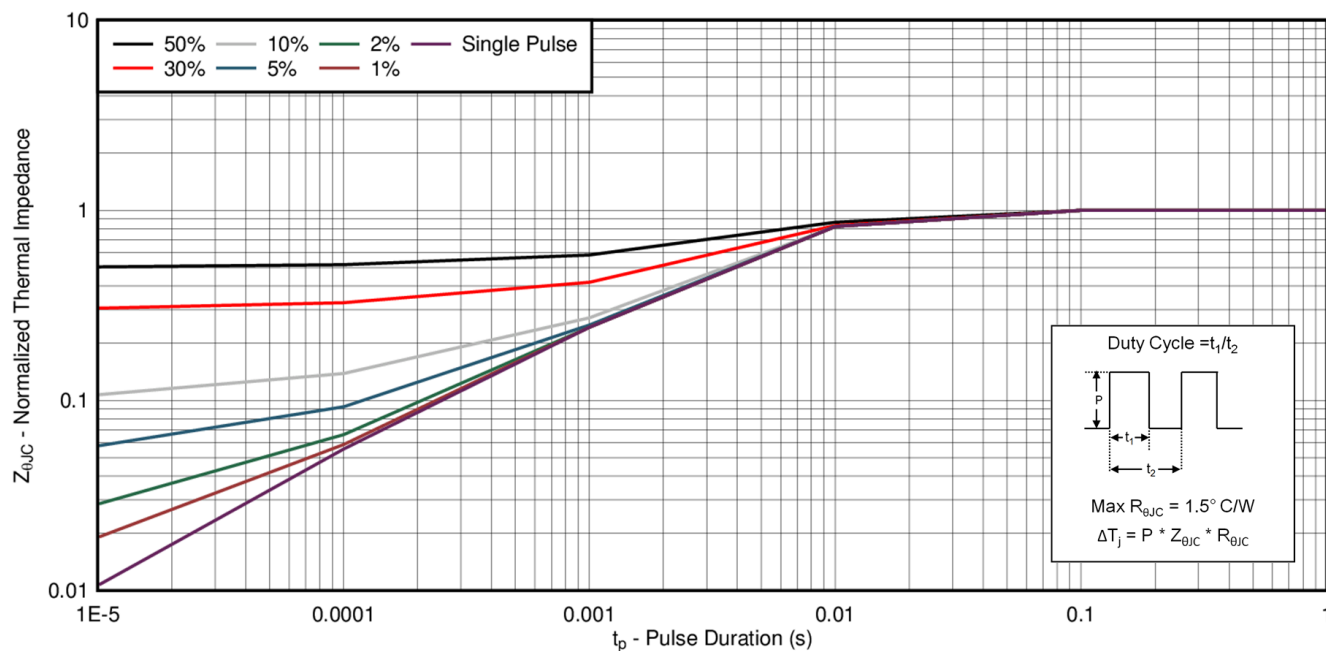


图 5-1. Transient Thermal Impedance

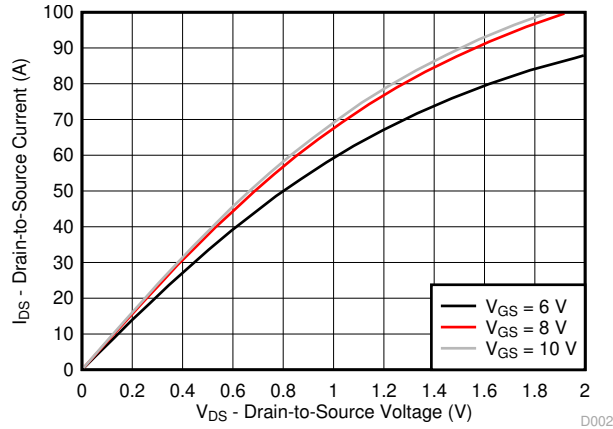


图 5-2. Saturation Characteristics

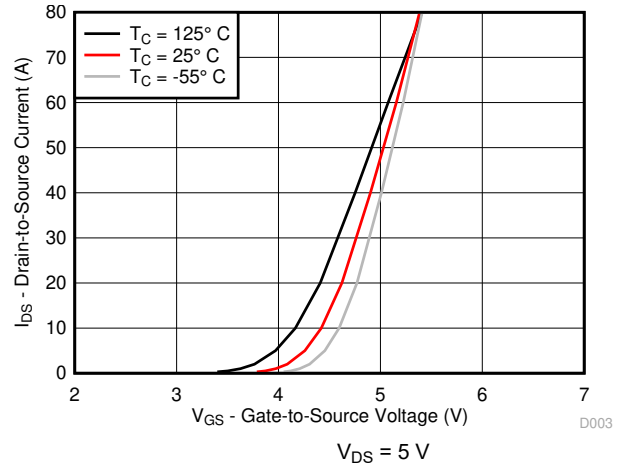


图 5-3. Transfer Characteristics

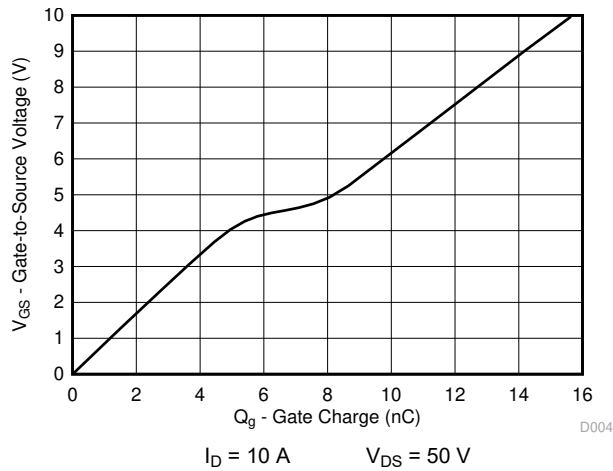


图 5-4. Gate Charge

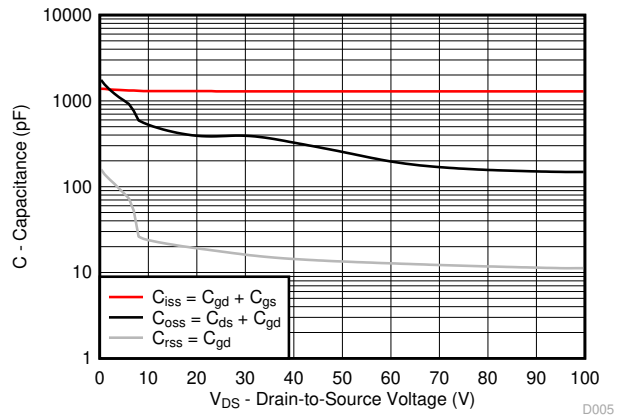


图 5-5. Capacitance

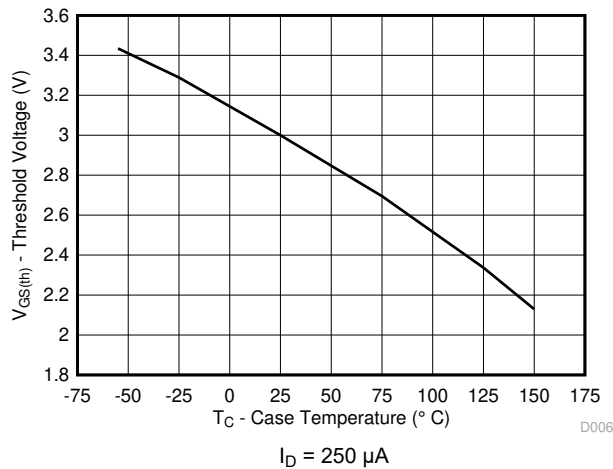


图 5-6. Threshold Voltage vs Temperature

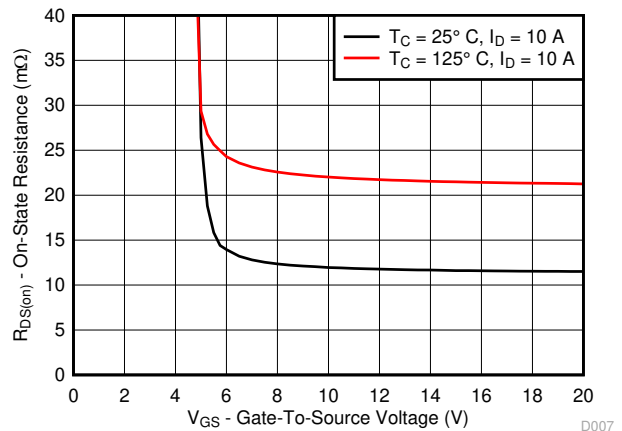


图 5-7. On-State Resistance vs Gate-to-Source Voltage

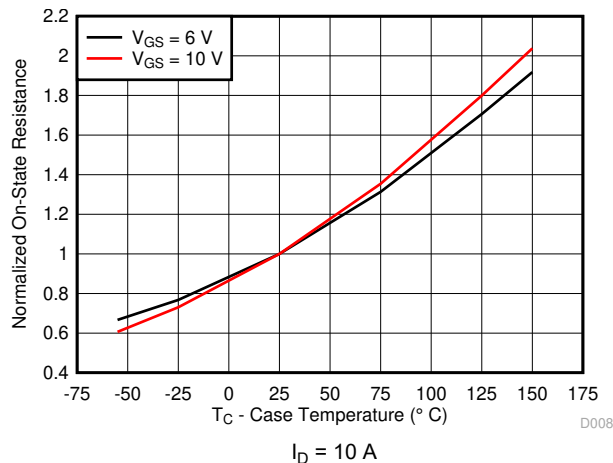


图 5-8. Normalized On-State Resistance vs Temperature

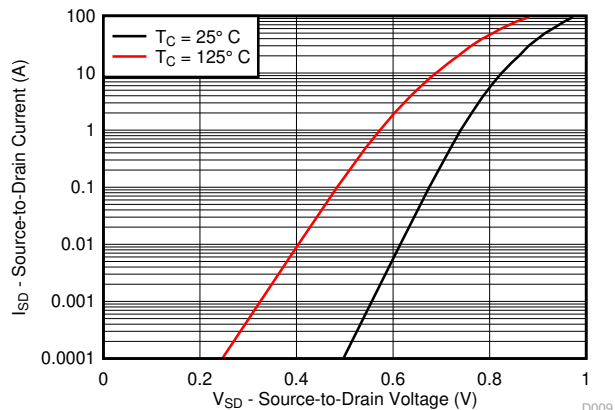


图 5-9. Typical Diode Forward Voltage

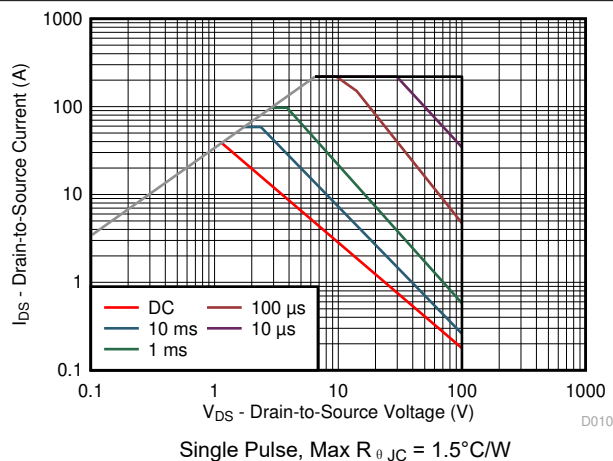


图 5-10. Maximum Safe Operating Area

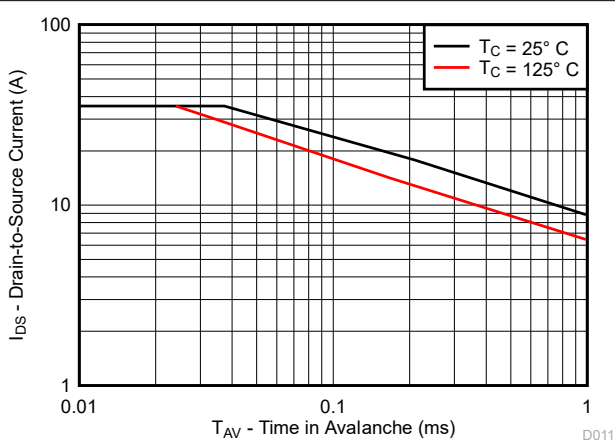


图 5-11. Single Pulse Unclamped Inductive Switching

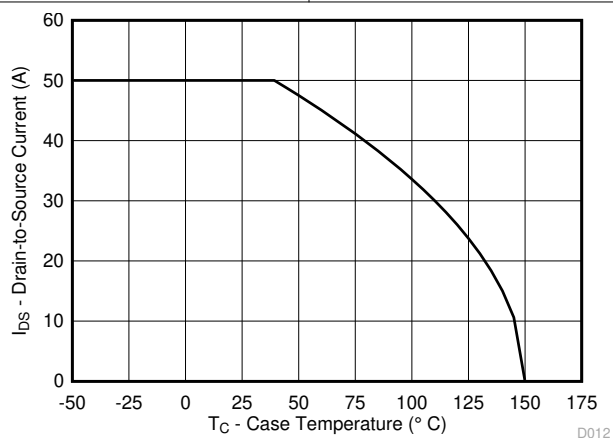


图 5-12. Maximum Drain Current vs Temperature

6 Device and Documentation Support

6.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

[TI E2E™ Online Community](#) TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

[Design Support](#) TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.2 Trademarks

NexFET™ is a trademark of Texas Instruments.

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6.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

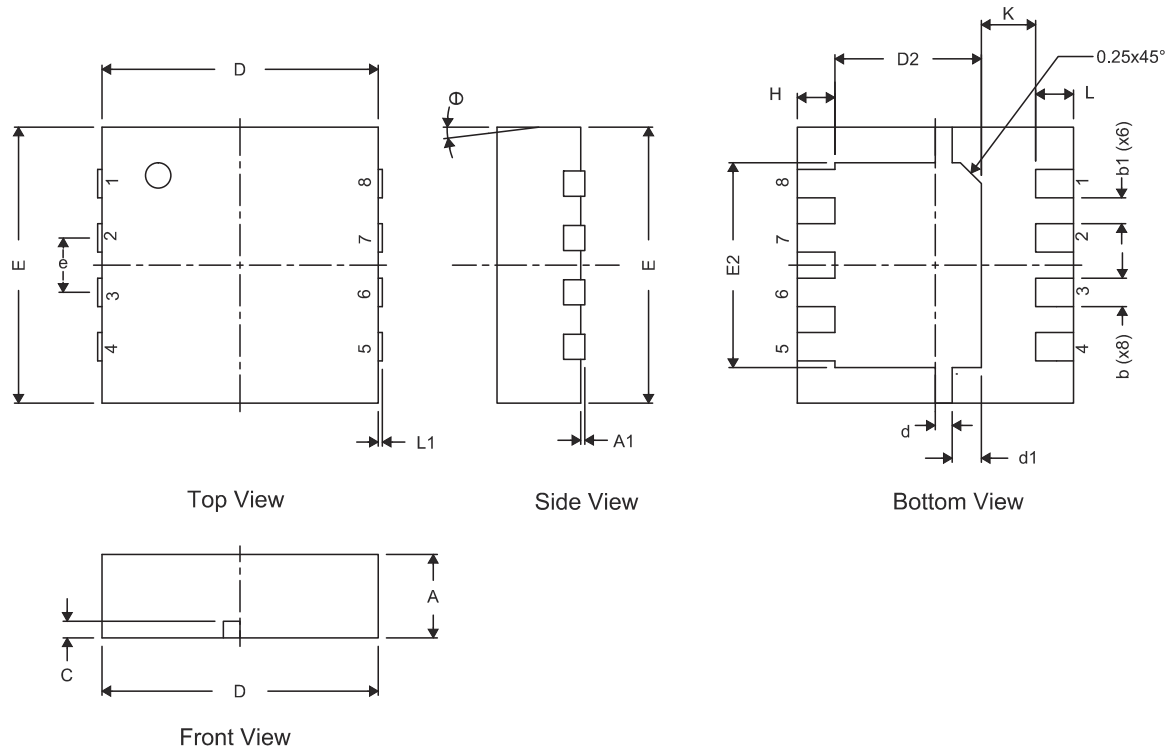
6.4 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

7 Mechanical, Packaging, and Orderable Information

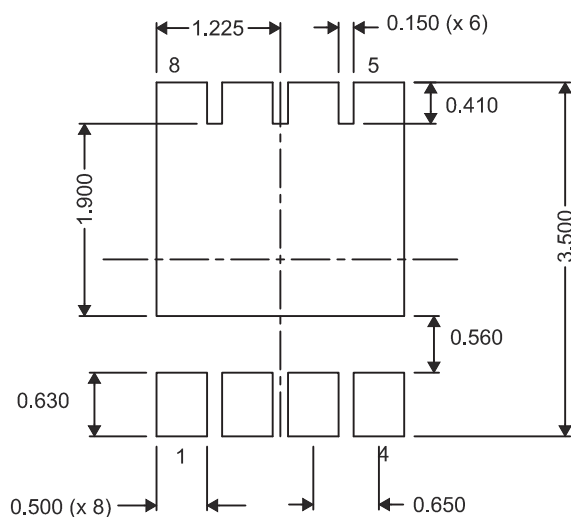
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

7.1 Q3 Package Dimensions



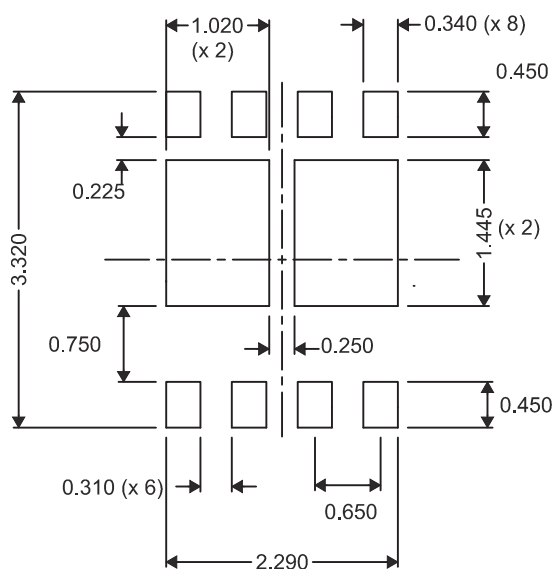
DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.950	1.000	1.100	0.037	0.039	0.043
A1	0.000	0.000	0.050	0.000	0.000	0.002
b	0.280	0.340	0.400	0.011	0.013	0.016
b1	0.310 NOM			0.012 NOM		
c	0.150	0.200	0.250	0.006	0.008	0.010
D	3.200	3.300	3.400	0.126	0.130	0.134
D2	1.650	1.750	1.800	0.065	0.069	0.071
d	0.150	0.200	0.250	0.006	0.008	0.010
d1	0.300	0.350	0.400	0.012	0.014	0.016
E	3.200	3.300	3.400	0.126	0.130	0.134
E2	2.350	2.450	2.550	0.093	0.096	0.100
e	0.650 TYP			0.026 TYP		
H	0.35	0.450	0.550	0.014	0.018	0.022
K	0.650 TYP			0.026 TYP		
L	0.35	0.450	0.550	0.014	0.018	0.022
L1	0	—	0	0	—	0
θ	0	—	0	0	—	0

7.2 Recommended PCB Pattern



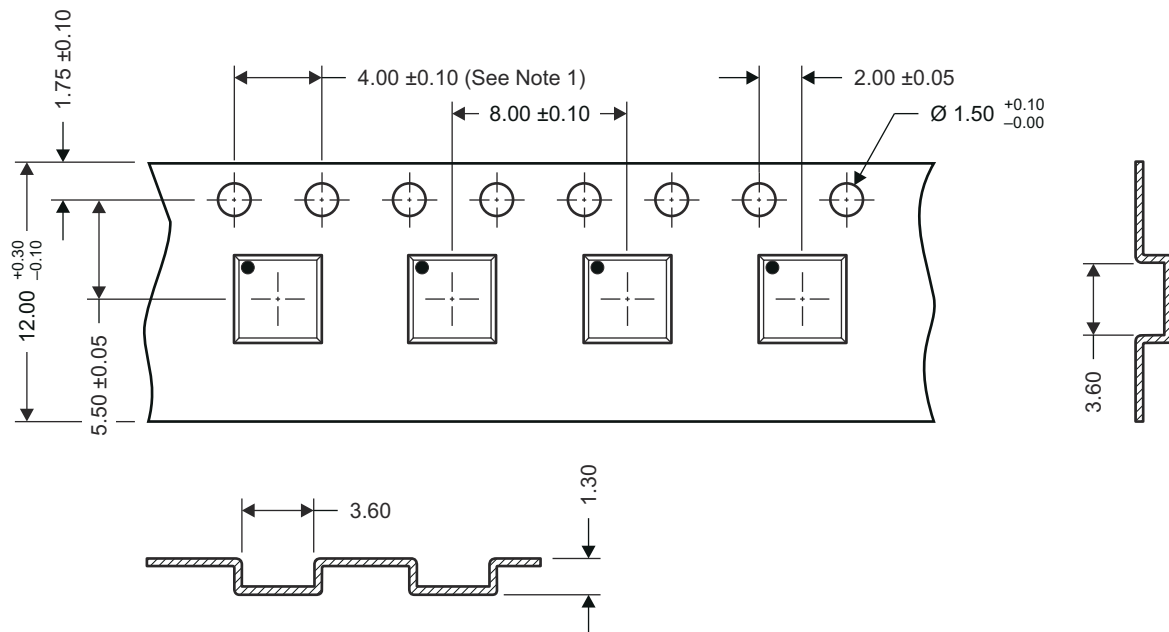
For recommended circuit layout for PCB designs, see application note [SLPA005](#) - *Reducing Ringing Through PCB Layout Techniques*.

7.3 Recommended Stencil Opening



All dimensions are in mm, unless otherwise specified.

7.4 Q3 Tape and Reel Information



M0144-01

Notes:

1. 10 sprocket hole pitch cumulative tolerance ± 0.2
2. Camber not to exceed 1 mm in 100 mm, noncumulative over 250 mm
3. Material: black static dissipative polystyrene
4. All dimensions are in mm (unless otherwise specified).
5. Thickness: 0.30 ± 0.05 mm
6. MSL1 260°C (IR and Convection) PbF-Reflow Compatible

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CSD19537Q3	Active	Production	VSON-CLIP (DQG) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD19537
CSD19537Q3.B	Active	Production	VSON-CLIP (DQG) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD19537
CSD19537Q3T	Active	Production	VSON-CLIP (DQG) 8	250 SMALL T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD19537
CSD19537Q3T.B	Active	Production	VSON-CLIP (DQG) 8	250 SMALL T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD19537

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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